# **Specification of Thermoelectric Module**

**TEC1-12712S** 

## **Description**

The 127 couples, 40 mm × 40 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

#### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

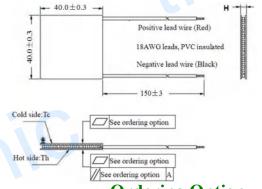
## **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

## **Performance Specification Sheet**

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	16.0	17.2	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	11.5	11.5	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	115.2	125.8	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	1.1	1.21	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

## Geometric Characteristics Dimensions in millimeters



# **Ordering Option**

# **Manufacturing Options**

#### A. Solder:

#### **B. Sealant:**

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt =  $240^{\circ}$ C)

3. EPS: Epoxy sealant

#### C. Ceramics:

#### **D.** Ceramics Surface Options:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

1. Blank ceramics (not metalized)

# Naming for the Module

Suffix	Thickness	Flatness/	Lead wire length(mm)
	(mm)	Parallelism (mm)	Standard/Optional length
TF	0:3.2±0.1	0:0.08/0.08	150±3/Specify
TF	1:3.2±0.03	1:0.03/0.03	150±3/Specify

Eg. TF01: Thickness  $3.2 \pm 0.1$  (mm) and Flatness 0.03/0.03 (mm)

Ceramics
—Flatness/ Parallelism
—Sealant
—Solder

TEC1-12712S—T100-NS —TF01 -AIO
T100: BiSn(Tmelt=138°C)

TEC1-12712S- X-X-X-X

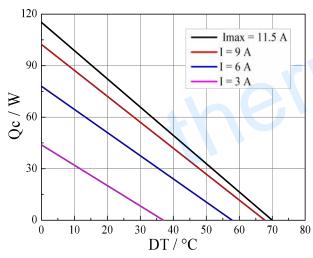
NS: No sealing AlO: Alumina white 96% TF01: Thickness  $\pm 0.1$ (mm) Flatness/Parallelism 0.025/0.025(mm)

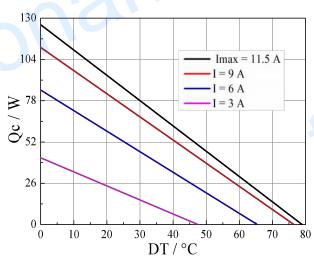
# **Specification of Thermoelectric Module**

## **TEC1-12712S**

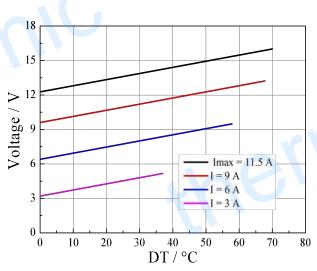
## Performance Curves at Th=27 °C

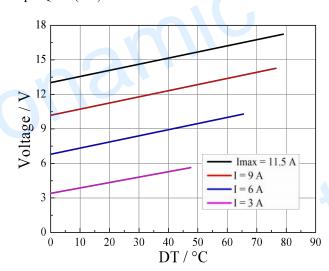
# Performance Curves at Th=50 °C



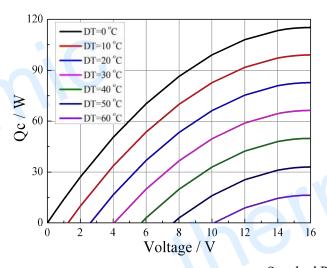


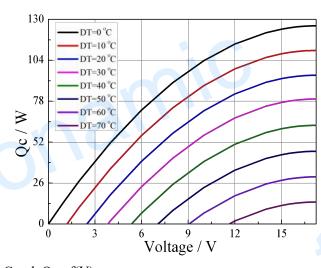
Standard Performance Graph Qc= f(DT)





Standard Performance Graph  $V = f(\Delta T)$ 

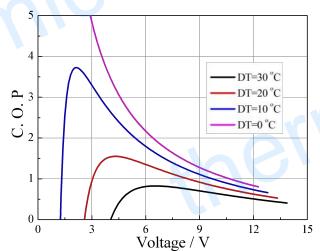




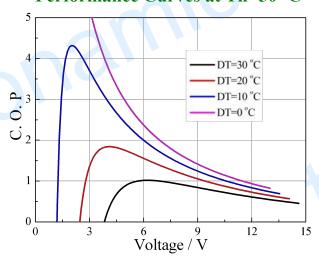
Standard Performance Graph Qc = f(V)

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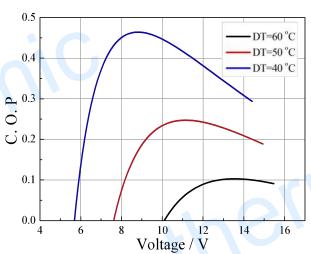
#### Performance Curves at Th=27 °C

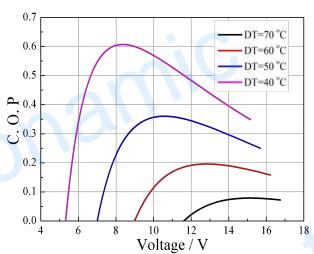


#### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

## **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Storage module below 100 °C
- Work under DC